What is claimed is:

1. A micromechanical component comprising:

a substrate (1);

a micromechanical functional plane (100) provided on the substrate;

a covering plane (200) provided on the micromechanical function plane (100); and

a printed circuit trace plane (300) provided on the covering plane (200);

wherein

the covering plane (200) features a monocrystalline region (14) which is epitaxially grown on an underlying monocrystalline region (7; 24); and

the covering plane (200) features a preferably polycrystalline region (15) which is epitaxially grown on an underlying polycrystalline starting layer (13) at the same time.

- The micromechanical component as recited in Claim 1, wherein the micromechanical functional plane (100) features a monocrystalline region (7) which is epitaxially grown on an underlying monocrystalline region (1), as well as a polycrystalline region (8) which is epitaxially grown on an underlying polycrystalline starting layer (6) at the same time.
- 3. The micromechanical component as recited in Claim 1,

wherein the micromechanical functional plane (100) features an SOI-type monocrystalline region (24) formed above an insulator layer (25) with the substrate (1).

- 4. The micromechanical component as recited in Claim 1, 2 or 3, wherein the monocrystalline region (14) of the covering plane (200) includes one or a plurality of integrated circuit elements (23) of an evaluation circuit or wiring elements.
- 5. The micromechanical component as recited in one of the preceding Claims, wherein the polycrystalline region (8) of the micromechanical functional plane (100) features a movable sensor structure (10).
- 6. The micromechanical component Claim 5,
 wherein the micromechanical functional plane (100)
 features a buried polysilicon layer (3) underneath the
 movable sensor structure (10).
- 7. The micromechanical component as recited in one of the preceding Claims, wherein one or a plurality of flip-chip connection elements, preferably gold bumps, are provided in the printed circuit trace plane (300).
- 8. The micromechanical component as recited in one of the preceding Claims, wherein it is possible to manufacture it by siliconsurface micromachining.
- 9. A method for manufacturing a micromechanical component comprising the steps of:

providing a substrate (1);

providing a micromechanical functional plane (100) on the substrate (1);

providing a covering plane (200) on the micromechanical functional plane (100);

providing a polysilicon starting layer (13) region-wise on the micromechanical functional plane (100), and leaving open region-wise a monocrystalline region (7, 24) of the micromechanical functional plane (100);

epitaxially depositing a monocrystalline region (14) on the monocrystalline region (7, 24) left open and epitaxially depositing a polycrystalline region (15) on the polycrystalline starting layer (13) at the same time; and

providing a printed circuit trace plane (300) on the covering plane (200).